



LPKF Contac RS and LPKF MiniContac RS **Professional PCB electroplating tanks**

- High quality through-hole plating for production or the lab
- Uniform copper deposition with Reverse Pulse Plating (RPP)
- No special chemical knowledge needed

Professional quality through-hole plating

The LPKF Contac RS and MiniContac RS, professional through-hole plating systems, are ideal for prototyping and small production run printed circuit boards, and their small footprints are perfect for labs and

production areas where space is a premium. Both systems feature Reverse Pulse Plating and reliable Blackhole® Technology for direct metallization.



LPKF Contac RS and LPKF MiniContac RS are practical table top systems.

Perfect for in-house rapid PCB prototyping

Easy to use

These microprocessor-controlled electroplating tanks feature a hands-on interface with a simple-to-use four-line display and menu-driven interface.

Easy process and simple chemistry

The through-hole plating process starts with a pre-treatment of the circuit boards. They are cleaned, degreased, pre-treated, and activated. A galvanic bath adds the copper coat and after another rinse and cleaning step, the boards are ready for soldering.

The LPKF MiniContac RS uses only four easy-to-change baths to complete a plating process. The LPKF Contac RS offers two additional baths: a rinsing bath and a bath for tin plating. No chemical knowledge or background is required to operate either system.

Choose the right tank for the right application!

Substrate size

LPKF MiniContac RS

230 mm (9")
330 mm (13")

LPKF Contac RS

460 mm (18")
330 mm (13")

Larger substrate!

Plating and tinning



copper



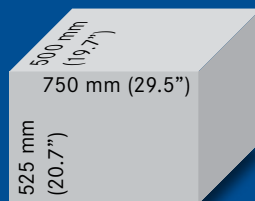
copper



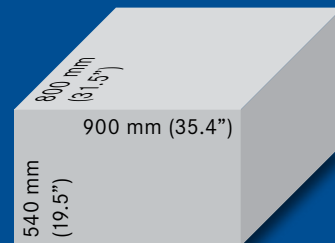
tin

Tinning available!

Dimensions



Compact!





Applications

Versatile plating technology

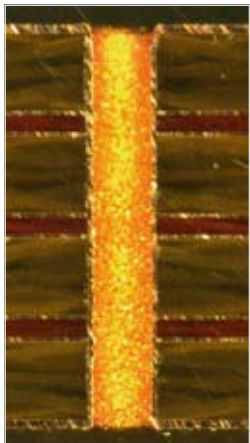
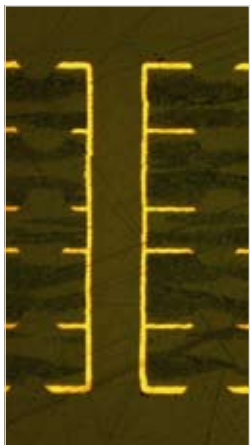


Plate most common circuit board materials, including FR4 (G10), FR5, and microwave substrates such as RO3000®, RO4000® and TMM®.

High-quality multilayer plating



Ideal for creating multilayer printed circuit boards.

Galvanic through-hole plating, step-by-step

The LPKF Contac RS and MiniContac RS are electroplating solutions ideal for any rapid PCB prototyping situation, identical in all but scale to professional PCB electroplating systems.

LPKF has automated the plating process as much as possible, using a step-by-step menu-driven system to walk a user through every step of the process. No particular chemistry background is necessary to operate a Contac RS or MiniContac RS – the instructions are simple and straightforward:

1. Washing and degreasing

The printed circuit board is washed and degreased in a cycle of baths to make absolutely sure that all contaminants are cleared away and that the electroplating process will function as cleanly as possible.

2. Activator application

A carbon activator is applied to the printed circuit board, adhering to all surfaces scheduled for plating.

3. Electroplating

The LPKF electroplating sequence includes full digital control over the process. User interaction is kept at an absolute minimum – the PCB is simply loaded in and the computer controls the rest of the process.

4. Final cleaning

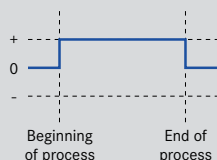
The final step of the process is a last cleaning of the PCB. After the printed circuit board is dry from the final rinse, it is ready for production. The total process requires two to three hours.

Advantage of Reverse Pulse Plating

Both systems feature Reverse Pulse Plating, which assures consistent, even coverage of conductor on the plated surface. This is especially useful for through-holes with high aspect ratios.

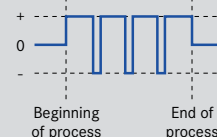
Typical electroplating

Typical electroplating uses current flowing in one single direction to perform the copper deposition.



Reverse Pulse Plating

With Reverse Pulse Plating, the electroplating process is punctuated by brief current reversals, preventing dimensional copper build-up that can cause trouble with high aspect ratio holes.



Specifications

	LPKF Contac RS	LPKF MiniContac RS
Part #	120742	119987
Activator	Carbon	Carbon
Max. substrate size	460 x 330 mm (18.0" x 13.0")	230 x 330 mm (9.0" x 13.0")
Max. board size	430 x 290 mm (16.9" x 11.4")	200 x 290 mm (7.9" x 11.4")
Hole diameter	>0.2 mm (8 mil)	>0.2 mm (8 mil)
Number of plated holes	Unlimited	Unlimited
Max. number of layers	6	6
Max. resistance	<10 m	<10 m
Environmental compatibility	Good	Good
Processing reliability	Very good	Very good
Process duration	Approx. 90-120 min	Approx. 90 min
Substrate types	FR4, RO3000®, RO4000®, TMM® *	FR4, RO3000®, RO4000®, TMM® *
Power supply	115/230 V, 50-60Hz, max. 1.5 kW	115/230 V, 50-60Hz, 0.6 kW
Ambient temperature	18-25 °C (64.4-77 °F)	18-25 °C (64.4-77 °F)
Dimensions (W/H/D)	900 x 540 x 800 mm (35.4" x 19.5" x 31.5")	750 x 525 x 500 mm (29.5" x 20.7" x 19.7")
Chemical tinning	Yes	No
Reverse pulse plating	Yes	Yes
Weight	85 kg (154 lbs) unfilled; 150 kg (330 lbs) filled	42 kg (92 lbs) unfilled; 71 kg (156 lbs) filled

* Further materials upon request.

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